

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Hiroyuki OSADA et al.

Application No.: 10/551,809

Confirmation No.: 6770

Filed: September 30, 2005

Art Unit: 1641

For: METHOD OF FIXING LOW-MOLECULAR
COMPOUND TO SOLID-PHASE SUPPORT

Examiner: L. V. Cook

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SEP 2 2008

Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated May 5, 2008, please amend the above-identified U.S. patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Abstract begin on page 5 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 6 of this paper.

Remarks/Arguments begin on page 10 of this paper.